CLAIMS

[1] A cover film comprising at least a substrate layer (A), an intermediate layer (B), and a heat seal layer (C) comprising a thermoplastic resin capable of heat sealing to carrier tape, wherein

the intermediate layer (B) comprises a metallocene linear low-density polyethylene, wherein the metallocene linear low-density polyethylene has a softening temperature of 98 to 109 °C by a TMA method according to JIS K7196.

[2] The cover film according to claim 1, comprising a peel layer (D) between the intermediate layer (B) and the heat seal layer (C), wherein one of the heat seal layer (C) and the peel layer (D) comprises a conductive material.

[3] The cover film according to claim 2, wherein the peel layer (D) comprises a hydrogenated aromatic vinyl-conjugated diene copolymer resin which has an aromatic vinyl group content of 15 to 35 mass% with respect to 100 mass% for the entire resin, and a density of 0.890×10^3 to 0.935×10^3 (kg/m^3).

[4] The cover film according to claim 2 or claim 3, wherein the conductive material is conductive microparticles, in the form of either acicular or spherical microparticles, or a combination thereof.

[5] An electronic component package using the cover film according to any one of claims 1 to 4 as the lid material for a thermoplastic resin carrier tape.

The invention claimed is:

1. A cover film comprising at least:

a substrate layer,

an intermediate layer,

a heat seal layer comprising a thermoplastic resin capable of heat sealing to carrier tape, and

a peel layer between the intermediate layer and the heat seal layer, wherein

the intermediate layer comprises a metallocene linear low-density polyethylene,

the metallocene linear low-density polyethylene has a softening temperature of 98 to 109° C. by a TMA method according to JIS K7196, and

the peel layer comprises a hydrogenated automatic vinyl-conjugated diene copolymer resin that has an aromatic vinyl group content of 15 to 35 mass % with respect to 100 mass % for the entire resin, and a density if 0.890×10^3 to 0.935×10^3 (kg/m^3).

2. The cover film according to claim 1, wherein one of the heat seal layer or the peel layer comprises a conductive material.

3. The cover film according to claim 2, wherein the conductive material is conductive microparticles, in the form of either acicular or spherical microparticles, or a combination thereof.

4. An electronic component package using the cover film according to claim 1 as the lid material for a thermoplastic resin carrier tape.

5. The cover film according to claim 2, wherein the heat seal layer comprises a conductive material.

6. The cover film according to claim 5, wherein

the heat seal layer comprises at least one of conductive tin oxide particles, conductive zinc oxide particles, or conductive titanium oxide particles that are conductive fillers, and

the peel layer comprises at least one of talc particles, silica particles, alumina particles, mica particles, calcium carbonate, or magnesium carbonate.